

IoT SuperServer SYS-211E-FRN2T

X13 2U Short-depth front I/O System with 2 x 10G ports, 2x 2.5" NVMe drive bays and redundant AC PSU



Key Applications

AI Inference and Machine Learning, Cloud Computing, Network Function Virtualization (NFV), 5G Networking,

Key Features

- Design with compliance to NEBS-Level 3;
- Single Socket E (LGA-4677) 5th/4th Gen Intel® Xeon® Scalable processors;
- 8 DIMM slots; Up to 2TB 3DS ECC DDR5-5600; R-DIMM/R-DIMM 3DS;
- Up to 3 PCIe 5.0 x16 FHHL, 1 PCIe 5.0 X16 HHHL & 1 PCIe 5.0 x8 FHHL expansion slots for Accelerator Add-On-Cards
Up to 6 Configurable PCIe 5.0 slots (4 standard + 2 optional);
- Onboard 2x 10GbE ports;
- 2x 2.5" NVMe drive bays;
- Redundant 800W AC Power Supplies;
- Ultra short depth, 2U Front I/O Edge Server;

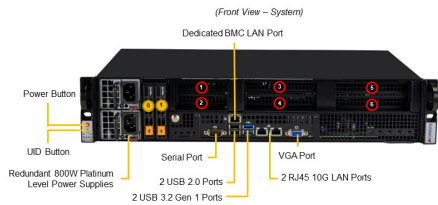


Form Factor	2U Rackmount Enclosure: 436.88 x 88.9 x 298.8mm (17.2" x 3.5" x 11.8") Package: 490 x 188 x 590mm (19.3" x 7.4" x 23.3")
Processor	Single Socket E (LGA-4677) 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors Up to 60C/120T; Up to 112.5MB Cache
GPU	Max GPU Count: Up to 3 single-width GPUs Supported GPU: NVIDIA PCIe: A2 Intel PCIe: Intel Data Center GPU Flex 140 CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect GPU-GPU Interconnect: PCIe
System Memory	Slot Count: 8 DIMM slots Max Memory (2DPC): Up to 2TB 5600MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 2 bays • 2 front hot-swap 2.5" NVMe drive bays M.2: 2 M.2 NVMe slots (M-key 2280/22110)
Expansion Slots	Default • 2 PCIe 5.0 x16 FHHL slots • 1 PCIe 5.0 x16 HHHL slot • 1 PCIe 5.0 x8 HHHL slot Option A* • 3 PCIe 5.0 x16 FHHL slots • 1 PCIe 5.0 x16 HHHL slot • 1 PCIe 5.0 x8 FHHL slot Option B* • 3 PCIe 5.0 x16 FHHL slots • 2 PCIe 5.0 x8 HHHL slots • 1 PCIe 5.0 x8 HHHL slot
On-Board Devices	NVMe: NVMe; RAID 0/1 support(Intel® VROC RAID key required) Chipset: Intel® C741 Network Connectivity: 2 QSFP28 25GbE with Intel® XXV710 (optional) 2 QSFP+ 40GbE with Intel® X710-BM2 (optional) 4 RJ45 1GbE with Intel® I350 (optional) 2 QSFP28 100GbE with Intel® E810-CAM2 (optional) 2 RJ45 10GBASE-T with Intel® X550 2 SFP+ 10GbE with Intel® X710-BM2 (optional) 2 QSFP56 100GbE (optional) 4 QSFP28 25GbE with Intel® E810-CAM1 (optional)

2 QSFP56 200GbE (optional)

Input / Output

LAN: 1 RJ45 1 GbE Dedicated BMC LAN port
2 RJ45 10 GbE LAN ports (Intel® X550-AT2)
USB: 2 USB 2.0 ports(front)
2 USB 3.2 Gen1 ports(front)
Video: 1 VGA port
Serial: 1 port

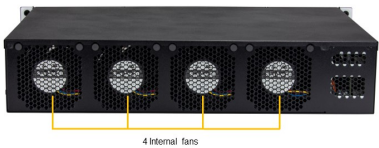


Drive Bay	Description
	Hot-swap 2.5" / 3.5" Drive Bays
	PCIe 5.0 x16 FHFL

Slot Description		
	Config 1 (Default)	Config 2 (Optional)
1	PCIe 5.0 x16 FHFL	PCIe 5.0 x16 FHFL
2	PCIe 5.0 x8 HHFL	---
3	---	PCIe 5.0 x16 FHFL
4	---	PCIe 5.0 x8 FHFL

**Config 2 and Config 3 require an optional rear card, cables and 12V/5V/3.3V CPU TDP is limited to 225W, and drive bays only support up to PCIe 5.0.

(Rear View – System)



System Cooling	Fans: Up to 4x 4-PIN PWM 8cm Fan(s) Air Shroud: 1 Air Shroud
Power Supply	2x 800W Redundant Platinum Level (94%) power supplies
System BIOS	BIOS Type: AMI 256MB SPI Flash
Management	SuperCloud Composer®; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU thermal trip support, PEPI
Dimensions and Weight	Weight: Gross Weight: 22 lbs (10 kg) Net Weight: 17 lbs (7.7 kg) Available Color: Silver/Black
Operating Environment	Operating Temperature: 0°C to 45°C (32°F to 113°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X13SEM-TF
Chassis	CSE-211M